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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of :
Haba, et al. :

Application No. 10/058,470 : Group Art Unit: 2841
: :
Filed: January 28, 2002 : Examiner: Not Yet Assigned
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For: COMPONENTS WITH : Date: April 22, 2002
RELEASABLE LEADS : X

Commissioner for Patents
Washington, D.C. 20231

**RESPONSE TO NOTICE TO FILE CORRECTED
APPLICATION PAPERS AND PRELIMINARY AMENDMENT**

Sir:

In response to the Notice to File Corrected Application Papers mailed April 2, 2002, Applicants hereby submit the following amendments and remarks.

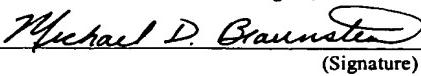
IN THE SPECIFICATION

CLEAN COPY OF AMENDED SPECIFICATION PARAGRAPHS:

Please amend paragraph [0044] as follows:

[0044] The starting structure may be fabricated by essentially any conventional process. For example, leads 24 may be formed by additive plating on polymeric layer 22 or by subtractive etching of a preexisting metal layer in contact with the polymeric layer. Conductors 34 may be formed by conventional plating processes for forming the liners in polymeric layers. The processes used to form the leads desirably provide the leads with good adhesion to the polymeric layer. For example, where the leads are formed by additive plating, an initial layer

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class mail in an envelope addressed to Commissioner for Patents, Washington, D.C. 20231 on April 22, 2002.


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